

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--------------------------------------|---|------------------|---------|------------------|
| L1 | 1064 | (205/215,219,660,684).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/06/19 16:05 |
| L2 | 145 | (rotat\$3 spin spun revolv\$3) and 1 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/06/19 16:17 |
| L3 | 334 | (puls\$3 alternat\$3 ac) and 1 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/06/19 16:17 |
| L4 | 3505 | (205/640-686).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/06/19 16:17 |
| L5 | 153 | 4 and seed | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/06/19 16:17 |
| L6 | 817 | (rotat\$3 spin spun revolv\$3) and 4 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/06/19 16:18 |
| L7 | 2966 | (205/205-219).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/06/19 16:18 |
| L8 | 757 | (pulse\$3 alternat\$3 ac) and 7 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/06/19 16:18 |

EAST Search History

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|----|-------|---|---|----|-----|------------------|
| S1 | 1135 | electrolytic adj clean\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 17:07 |
| S2 | 52064 | ("205").CLAS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/07/25 12:57 |
| S3 | 282 | S1 and S2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/25 12:58 |
| S4 | 5 | electropolish with clean | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/25 13:08 |
| S5 | 2 | ("20020074242").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/07/25 13:00 |
| S6 | 8 | electropolish with cleaning | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/25 13:09 |
| S7 | 0 | taiwan adj semiconductor adj manufacturing.ti. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 16:44 |
| S8 | 1 | electropolish with seed adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/28 14:28 |

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|-----|-----|--|---|----|-----|------------------|
| S9 | 815 | polish\$5 with seed adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 16:45 |
| S10 | 35 | electropolish\$5 with seed adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 17:01 |
| S11 | 815 | polish\$5 with seed adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 16:57 |
| S12 | 114 | polish\$5 near5 seed adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 16:58 |
| S13 | 12 | electrolytic adj polish\$5 with seed adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 17:13 |
| S14 | 2 | ("20020068438").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/01 17:24 |
| S15 | 502 | planariz\$5 with seed adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 17:25 |
| S16 | 72 | planariz\$5 near5 seed adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 17:25 |

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|-----|------|--|---|----|----|------------------|
| S17 | 0 | electrolytic adj clean\$3 same seed adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 17:48 |
| S18 | 49 | electrolytic adj clean\$3 same substrate | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 17:33 |
| S19 | 56 | electrolytic adj clean\$3 adj method | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 17:33 |
| S20 | 17 | electrolytic adj clean\$3 with (via vias trench trenches) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 17:45 |
| S21 | 4 | electrolytic adj clean\$3 with remov\$5 with particle | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 17:45 |
| S22 | 1047 | clean\$3 same seed adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 17:48 |
| S23 | 470 | clean\$3 with seed adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 17:48 |
| S24 | 530 | clean\$3 with via adj opening | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 17:48 |

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|-----|---------|---|---|----|----|------------------|
| S25 | 238 | clean\$3 near8 via adj opening | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 17:52 |
| S26 | 231 | clean\$3 near8 seed adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/01 17:52 |
| S27 | 0 | qingtang | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/09 18:02 |
| S28 | 20256 | jiang | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/09 18:02 |
| S29 | 23 | tobby | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/09 18:02 |
| S30 | 745 | semiconductor.as. and internat\$6. as. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/09 18:06 |
| S31 | 1369783 | clean\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/09 18:03 |
| S32 | 197 | S30 and S31 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/09 18:03 |

EAST Search History

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|-----|--------|---|---|----|-----|------------------|
| S33 | 548842 | clean\$3.ab. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/09 18:03 |
| S34 | 20 | S30 and S33 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/09 18:03 |
| S35 | 79750 | ("204").CLAS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/09 18:06 |
| S36 | 52118 | ("205").CLAS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/09 18:05 |
| S37 | 15556 | S35 and S36 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/09 18:06 |
| S38 | 2138 | semiconductor.as. and (internat\$6. as. int.as.) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/09 18:06 |
| S39 | 3 | S37 and S38 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/28 14:27 |
| S40 | 2 | ("20030201185").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/10 14:34 |

EAST Search History

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|-----|--------|---|---|----|-----|------------------|
| S41 | 2 | ("6309528").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/10 14:34 |
| S42 | 2 | ("6652727").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/10 14:34 |
| S43 | 2 | ("6793796").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/10 14:49 |
| S44 | 214157 | (polyethylene polypropylene) adj glycol | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 15:20 |
| S45 | 336016 | surfactant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 14:53 |
| S46 | 19440 | S44 with S45 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 14:53 |
| S47 | 24062 | non adj ionic adj surfactant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 14:53 |
| S48 | 8677 | S44 and S47 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 14:56 |

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|-----|-------|--|---|----|-----|------------------|
| S49 | 79750 | ("204").CLAS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/10 14:54 |
| S50 | 52118 | ("205").CLAS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/10 14:54 |
| S51 | 15556 | S49 and S50 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 16:47 |
| S52 | 3 | S44 and S47 and S51 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 14:54 |
| S53 | 2382 | S44 with S47 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 14:57 |
| S54 | 1 | S53 and S51 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 14:56 |
| S55 | 118 | (polyethylene polypropylene) adj glycol with electroplating | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 15:23 |
| S56 | 36460 | (polyethylene polypropylene) adj glycol with molecular adj weight | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 15:23 |

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|-----|------|--|---|----|----|------------------|
| S57 | 343 | (polyethylene polypropylene) adj glycol with molecular adj weight and electroplating | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 16:14 |
| S58 | 1954 | (polyethylene polypropylene) adj glycol with alkanol | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 16:15 |
| S59 | 18 | (polyethylene polypropylene) adj glycol with alkanol and electroplating | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 16:44 |
| S60 | 9815 | copper adj sulfate and sulfuric adj acid | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 16:44 |
| S61 | 2130 | copper adj sulfate and sulfuric adj acid and electroplating | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 16:44 |
| S62 | 226 | copper adj sulfate and sulfuric adj acid and electroplating and S51 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 16:46 |
| S63 | 1430 | copper adj sulfate and sulfuric adj acid and (polyethylene polypropylene) adj glycol | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 16:47 |
| S64 | 39 | copper adj sulfate and sulfuric adj acid and (polyethylene polypropylene) adj glycol and S51 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 16:47 |

EAST Search History

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|-----|--------|--|---|----|-----|------------------|
| S65 | 116312 | S49 S50 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 16:47 |
| S66 | 266 | copper adj sulfate and sulfuric adj acid and (polyethylene polypropylene) adj glycol and S65 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 16:48 |
| S67 | 71 | copper adj sulfate and sulfuric adj acid and (polyethylene polypropylene) adj glycol with molecular adj weight and S65 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/10 16:48 |
| S68 | 2 | ("0221315").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:15 |
| S69 | 1 | method adj electroplating adj copper with formed adj diluting | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/11 11:26 |
| S70 | 2 | ("5715133").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 11:26 |
| S71 | 12 | ("3779877" "4276129" "4279714" "4609971" "5143591" "5503718").PN. OR ("5715133").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/08/11 11:26 |
| S72 | 583 | (205/709-716).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/28 15:02 |

EAST Search History

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|-----|--------|--|---|----|-----|------------------|
| S73 | 757816 | interconnect damascene seed adj layer wafer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/28 11:04 |
| S74 | 6 | S72 and S73 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/28 11:05 |
| S75 | 2 | ("5,232,563").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/28 12:50 |
| S76 | 2 | ("5807165").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/28 12:51 |
| S77 | 3469 | (205/640-686).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/28 12:51 |
| S78 | 0 | S76 and S77 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/28 12:51 |
| S79 | 2 | ("0221315").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/28 14:27 |
| S80 | 39 | "221315" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/28 14:27 |

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|-----|---------|--|---|----|-----|------------------|
| S81 | 230 | shanghai.as. and semiconductor.as. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/28 14:29 |
| S82 | 19 | shanghai.as. and semiconductor.as. and copper | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/28 14:41 |
| S83 | 2 | ("6689686").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/28 14:42 |
| S84 | 0 | ("6689686").URPN. | USPAT | OR | ON | 2005/12/28 14:42 |
| S85 | 4623011 | electroplat\$3 plat\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/28 15:02 |
| S86 | 583 | (205/709-716).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/28 15:02 |
| S87 | 185 | S85 and S86 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/28 15:08 |
| S88 | 2 | ("6297155").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/28 15:10 |
| S89 | 2 | ("6340633").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/28 15:11 |

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|-----|-----|--|---|----|-----|------------------|
| S90 | 2 | ("6399479").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/28 15:12 |
| S91 | 69 | (205/87).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/28 15:12 |
| S92 | 1 | ecmp with electroplat\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 17:08 |
| S93 | 16 | ecmp same electroplat\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 17:18 |
| S94 | 310 | uzoh.in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 17:19 |
| S95 | 139 | uzoh.in. and chemical adj mechanical | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 17:20 |
| S96 | 87 | uzoh.in. and cap\$4 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 17:26 |
| S97 | 35 | datta.in. and chemical adj mechanical | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 17:26 |

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|----------|------|--|---|----|-----|------------------|
| S98 | 1 | datta.in. and chemical adj mechanical and puls\$2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 17:27 |
| S99 | 891 | ecmp electrochemical adj mechanical | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 17:27 |
| S10 0 | 161 | S99 and puls\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 17:34 |
| S10 1 | 42 | S99 and puls\$3 and copper adj sulfate | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 17:37 |
| S10 2 | 40 | chen.in. and chemical adj mechanical and waveform | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 17:42 |
| S10 3 | 1329 | chemical adj mechanical and waveform | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 17:42 |
| S10 4 | 3470 | (205/640-686).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/30 17:42 |
| S10 5 | 24 | S103 and S104 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 18:17 |

EAST Search History

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| S10 6 | 66 | copper adj sulfate and electrochemical adj mechanical adj polish\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 18:01 |
| S10 7 | 0 | copper adj sulfate with inexpensive and electrochemical adj mechanical adj polish\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 18:01 |
| S10 8 | 0 | copper adj sulfate with inexpensive and electropolish\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 18:02 |
| S10 9 | 21 | copper adj sulfate with inexpensive | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/31 11:56 |
| S11 0 | 2 | ("20030209448").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/30 21:13 |
| S11 1 | 2 | ("20050155869").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/30 19:04 |
| S11 2 | 468 | (205/219).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/30 19:05 |
| S11 3 | 69 | (205/87).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/30 19:05 |

EAST Search History

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|----------|------|-------------------------------|---|----|----|------------------|
| S11 4 | 12 | puls\$3 and S113 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 19:14 |
| S11 5 | 1612 | c25d005/34.ipc. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 19:15 |
| S11 6 | 688 | c25d005/36.ipc. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 19:15 |
| S11 7 | 209 | c25d005/38.ipc. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 19:15 |
| S11 8 | 67 | c25d005/40.ipc. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 19:15 |
| S11 9 | 106 | c25d005/42.ipc. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 19:15 |
| S12 0 | 545 | c25d005/44.ipc. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 19:15 |
| S12 1 | 3123 | S115 S116 S117 S118 S119 S120 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 19:15 |

EAST Search History

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| S12 2 | 72 | S121 and puls\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 19:16 |
| S12 3 | 72 | S121 and puls\$3 not S114 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 19:35 |
| S12 4 | 3 | ("9947731").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/30 19:35 |
| S12 5 | 2 | ("4524598").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/30 19:41 |
| S12 6 | 422 | (205/223).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/30 19:41 |
| S12 7 | 33 | S126 and puls\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 19:42 |
| S12 8 | 15 | S126 and puls\$3 and seed | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 19:42 |
| S12 9 | 20 | uzoh.in. and (capping capped) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 20:43 |

EAST Search History

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| S13 0 | 3470 | (205/640-686).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/30 21:14 |
| S13 1 | 18 | pulse adj reverse and S130 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 21:31 |
| S13 2 | 1032 | seed adj layer with angstroms | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 21:31 |
| S13 3 | 161 | seed adj layer with angstroms with "200" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 21:32 |
| S13 4 | 335 | seed adj layer with angstroms and damascene | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 21:32 |
| S13 5 | 115 | seed adj layer with angstroms same damascene | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/30 21:33 |
| S13 6 | 2 | "20050155869" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/31 10:35 |
| S13 7 | 630 | (205/215,219).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/31 10:13 |

EAST Search History

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| S13 8 | 260133 | seed | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/31 10:13 |
| S13 9 | 19 | S137 and S138 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/31 10:13 |
| S14 0 | 468 | (205/219).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/31 10:35 |
| S14 1 | 44 | rotat\$3 and S140 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/31 10:36 |
| S14 2 | 0 | rotat\$3 with friction and S140 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/31 10:38 |
| S14 3 | 51799 | rotat\$3 with particle | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/31 10:38 |
| S14 4 | 189 | (205/215).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/31 10:38 |
| S14 5 | 25 | rotat\$3 and S144 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/31 10:39 |

EAST Search History

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| S14 6 | 5 | rotat\$3 and S144 and seed | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/31 11:05 |
| S14 7 | 2 | ("20030201185").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/31 11:17 |
| S14 8 | 1 | rotat\$3 with lamellar adj flow | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/31 11:19 |
| S14 9 | 24594 | (205/80-333).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/31 11:19 |
| S15 0 | 62325 | rotat\$3 with uniform | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/31 11:19 |
| S15 1 | 281 | S150 and S149 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/31 11:19 |
| S15 2 | 104 | S150 and S149 and wafer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/31 11:56 |
| S15 3 | 52522 | ("205").CLAS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/31 11:57 |

EAST Search History

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| S15 4 | 21 | copper adj sulfate with inexpensive | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/31 11:57 |
| S15 5 | 0 | S153 and S154 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/31 11:57 |
| S15 6 | 2 | ("20050155869").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/06/09 15:47 |